

Title (en)

Bath for electroplating copper-tin alloys

Title (de)

Bad zum galvanischen Abscheiden von Kupfer-Zinn-Legierungen

Title (fr)

Bain d'électrodéposition d'alliages cuivre-étain

Publication

EP 0698676 B1 19970924 (DE)

Application

EP 95104355 A 19950324

Priority

DE 4426914 A 19940729

Abstract (en)

[origin: DE4426914C1] Bath for galvanically depositing Cu-Sn alloys, consisting of H₂O, Cu-cyanide, Sn (IV) cpd, alkali metal-cyanide, -hydroxide and complex former and additionally contg. alkali metal phosphate, contains the K-salt of gluconic acid, gluconic acid and/or glucuronic acid as complex former and has a pH of 8-14.

IPC 1-7

C25D 3/40; **C25D 3/32**

IPC 8 full level

C25D 3/32 (2006.01); **C25D 3/40** (2006.01); **C25D 3/58** (2006.01); **C25D 3/60** (2006.01)

CPC (source: EP)

C25D 3/58 (2013.01); **C25D 3/60** (2013.01)

Cited by

CN104962959A; IT202100008084A1

Designated contracting state (EPC)

CH DE FR GB IT LI

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DE 4426914 C1 19950817; DE 59500711 D1 19971030; EP 0698676 A1 19960228; EP 0698676 B1 19970924

DOCDB simple family (application)

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